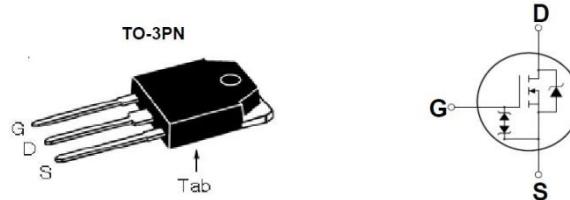


## Features

- Low gate charge
- 100% avalanche tested
- Improved dv/dt capability
- RoHS compliant
- JEDEC Qualification
- Improved ESD performance

N-channel MOSFET

$BV_{DSS}$	$I_D$	$R_{DS(on)}$
800V	12A	< 0.65Ω



Device	Package	Marking	Remark
GP2M012A080NG	TO-3PN	GP2M012A080NG	RoHS

## Absolute Maximum Ratings

Parameter	Symbol	value	Unit
Drain-Source Voltage	$V_{DS}$	800	V
Gate-Source Voltage	$V_{GS}$	±30	V
Continuous Drain Current  $T_C = 25\text{ °C}$	$I_D$	12	A
		10	A
Pulsed Drain Current (Note 1)	$I_{DM}$	48	A
Single Pulse Avalanche Energy (Note 2)	$E_{AS}$	313	mJ
Repetitive Avalanche Current (Note 1)	$I_{AR}$	12	A
Repetitive Avalanche Energy (Note 1)	$E_{AR}$	41.6	mJ
Power Dissipation  $T_C = 25\text{ °C}$	$P_D$	416	W
		3.3	W/°C
Peak Diode Recovery dv/dt (Note 3)	dv/dt	4.5	V/ns
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55~150	°C
Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	$T_L$	300	°C

\* Limited only by maximum junction temperature

## Thermal Characteristics

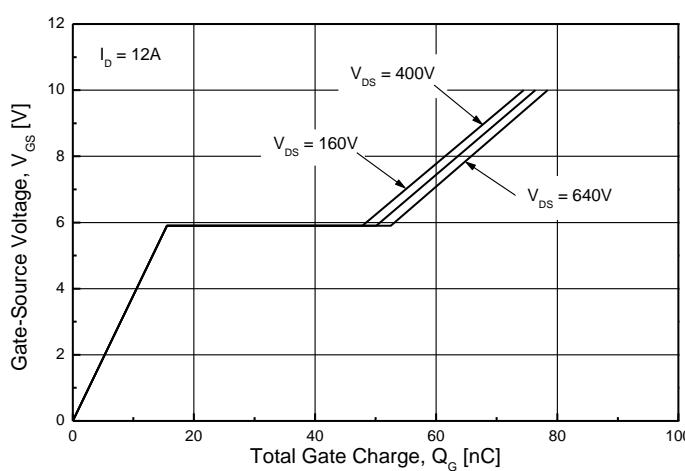
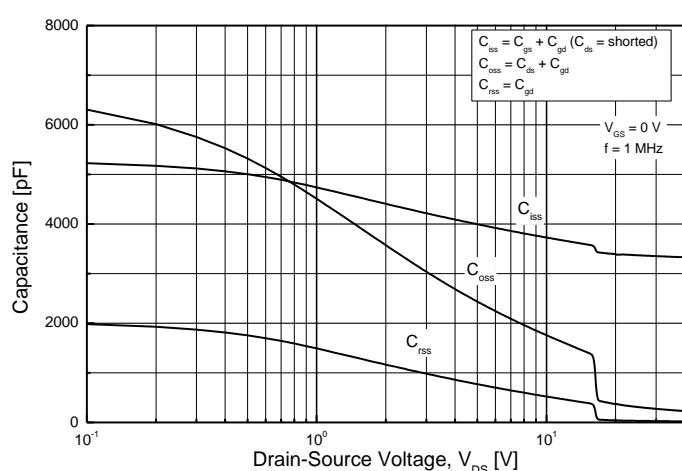
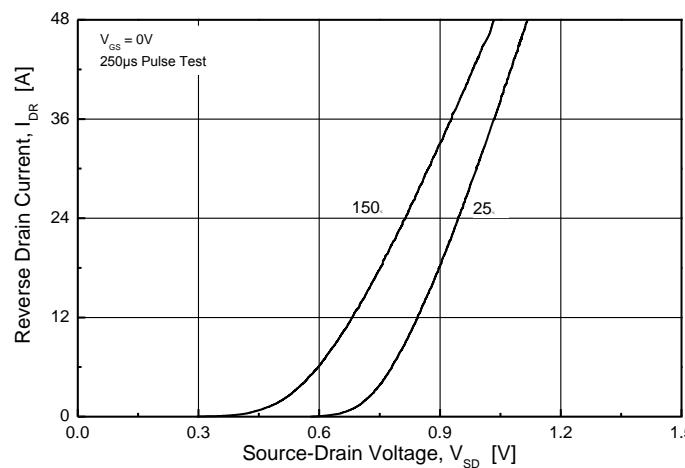
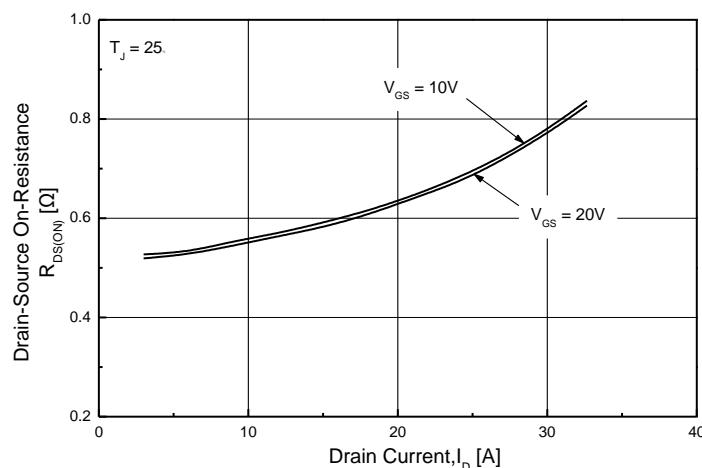
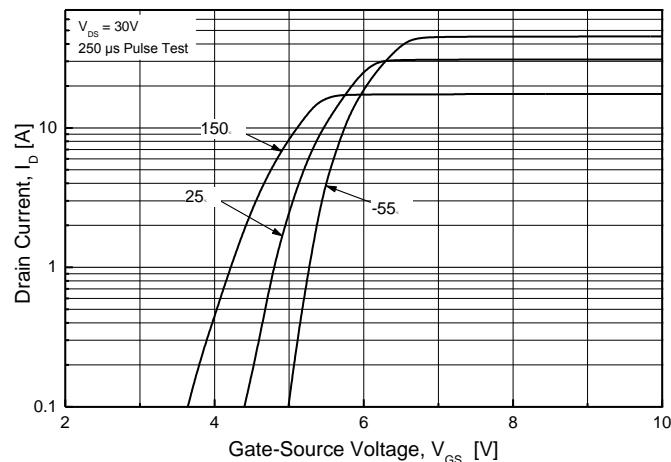
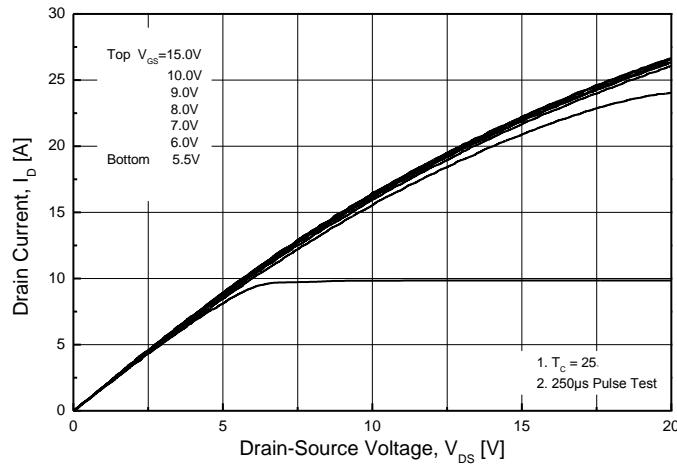
Parameter	Symbol	value	Unit
Maximum Thermal resistance, Junction-to-Case	$R_{\theta JC}$	0.3	°C/W
Maximum Thermal resistance, Junction-to-Ambient	$R_{\theta JA}$	62.5	°C/W

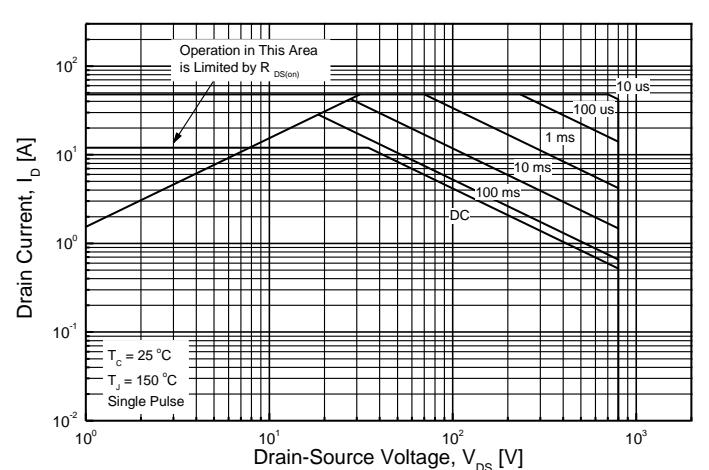
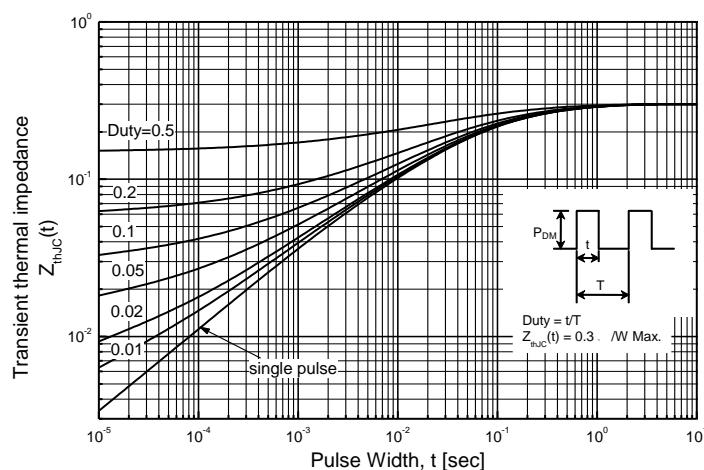
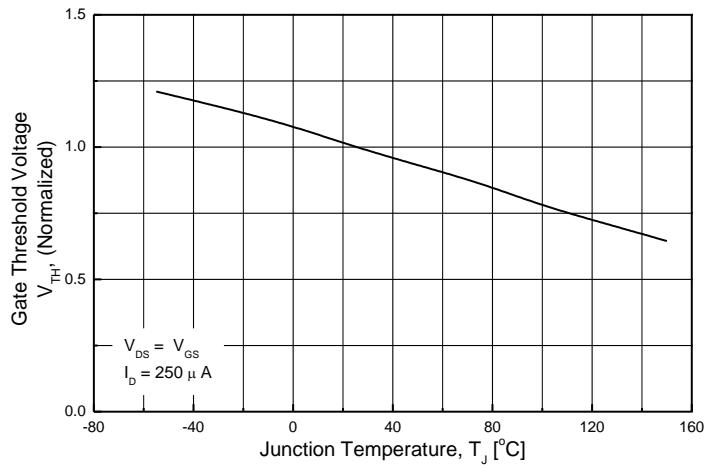
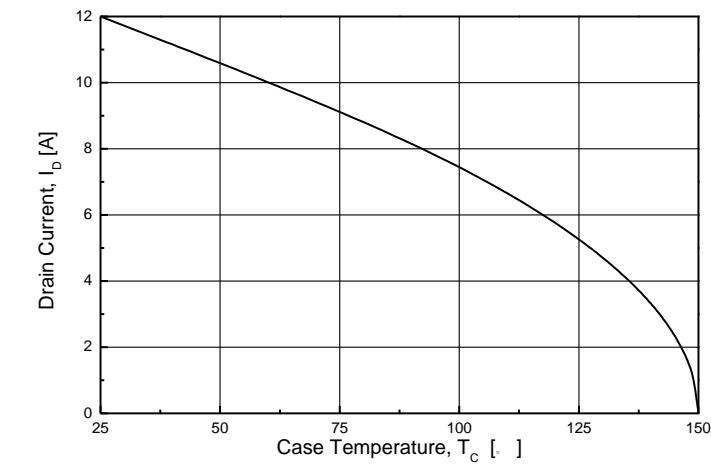
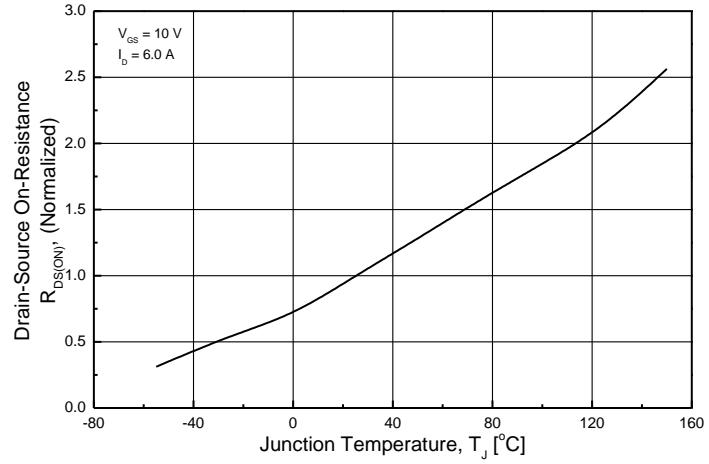
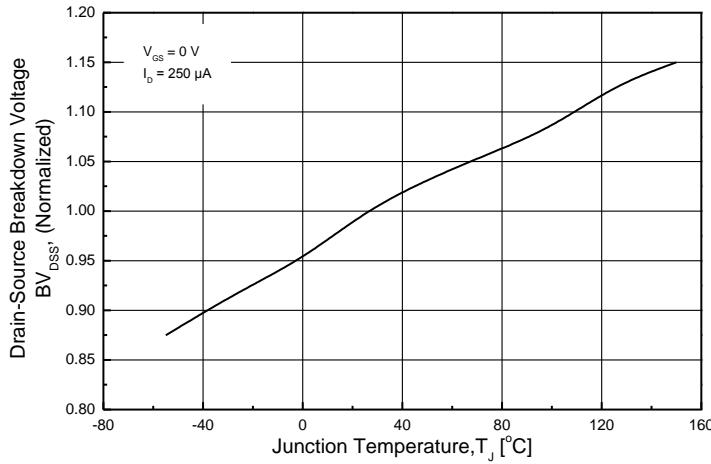
**Electrical Characteristics :  $T_c=25^\circ\text{C}$ , unless otherwise noted**

Parameter	Symbol	Test condition	Min	Typ	Max	Units
<b>OFF</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}} = 0 \text{ V}, I_{\text{D}} = 250 \mu\text{A}$	600	--	--	V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}} = 800 \text{ V}, V_{\text{GS}} = 0 \text{ V}$	--	--	1	$\mu\text{A}$
		$V_{\text{DS}} = 640 \text{ V}, T_c = 125^\circ\text{C}$	--	--	10	$\mu\text{A}$
Forward Gate-Source Leakage Current	$I_{\text{GSSF}}$	$V_{\text{GS}} = 30 \text{ V}, V_{\text{DS}} = 0 \text{ V}$	--	--	100	$\mu\text{A}$
Reverse Gate-Source Leakage Current	$I_{\text{GSSR}}$	$V_{\text{GS}} = -30 \text{ V}, V_{\text{DS}} = 0 \text{ V}$	--	--	-100	$\mu\text{A}$
<b>ON</b>						
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{DS}} = V_{\text{GS}}, I_{\text{D}} = 250 \mu\text{A}$	3	--	5	V
Drain-Source On-Resistance	$R_{\text{DS(on)}}$	$V_{\text{GS}} = 10 \text{ V}, I_{\text{D}} = 6.0 \text{ A}$	--	0.53	0.65	$\Omega$
Forward Transconductance <sup>(Note 4)</sup>	$g_{\text{FS}}$	$V_{\text{DS}} = 30 \text{ V}, I_{\text{D}} = 6.0 \text{ A}$	--	18	--	S
<b>DYNAMIC</b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}} = 25 \text{ V}, V_{\text{GS}} = 0 \text{ V}, f = 1.0 \text{ MHz}$	--	3370	--	pF
Output Capacitance	$C_{\text{oss}}$		--	310	--	pF
Reverse Transfer Capacitance	$C_{\text{rss}}$		--	33	--	pF
<b>SWITCHING</b>						
Turn-On Delay Time <sup>(Note 4,5)</sup>	$t_{\text{d(on)}}$	$V_{\text{DD}} = 400 \text{ V}, I_{\text{D}} = 12 \text{ A}, R_{\text{G}} = 25 \Omega$	--	81	--	ns
Turn-On Rise Time <sup>(Note 4,5)</sup>	$t_{\text{r}}$		--	90	--	ns
Turn-Off Delay Time <sup>(Note 4,5)</sup>	$t_{\text{d(off)}}$		--	266	--	ns
Turn-Off Fall Time <sup>(Note 4,5)</sup>	$t_{\text{f}}$		--	63	--	ns
Total Gate Charge <sup>(Note 4,5)</sup>	$Q_{\text{g}}$	$V_{\text{DS}} = 640 \text{ V}, I_{\text{D}} = 12 \text{ A}, V_{\text{GS}} = 10 \text{ V}$	--	79	--	nC
Gate-Source Charge <sup>(Note 4,5)</sup>	$Q_{\text{gs}}$		--	16	--	nC
Gate-Drain Charge <sup>(Note 4,5)</sup>	$Q_{\text{gd}}$		--	37	--	nC
<b>SOURCE DRAIN DIODE</b>						
Maximum Continuous Drain-Source Diode Forward Current	$I_{\text{s}}$	---	--	--	12	A
Maximum Pulsed Drain-Source Diode Forward Current	$I_{\text{SM}}$	---	--	--	48	A
Drain-Source Diode Forward Voltage	$V_{\text{SD}}$	$V_{\text{GS}} = 0 \text{ V}, I_{\text{s}} = 12 \text{ A}$	--	--	1.5	V
Reverse Recovery Time <sup>(Note 4)</sup>	$t_{\text{rr}}$	$V_{\text{GS}} = 0 \text{ V}, I_{\text{s}} = 12 \text{ A}$ $dI_{\text{F}} / dt = 100 \text{ A}/\mu\text{s}$	--	528	--	ns
Reverse Recovery Charge <sup>(Note 4)</sup>	$Q_{\text{rr}}$		--	6.7	--	$\mu\text{C}$

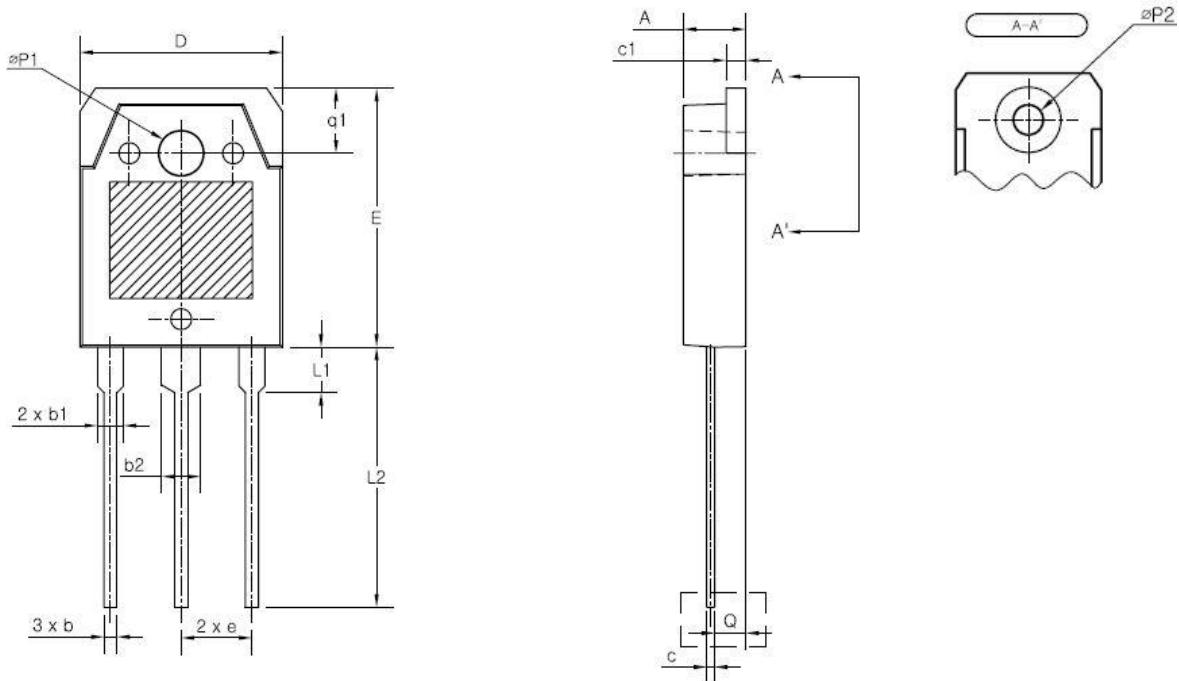
Note :

1. Repeated rating : Pulse width limited by safe operating area
2.  $L = 4.08 \text{ mH}, I_{\text{AS}} = 12 \text{ A}, V_{\text{DD}} = 50 \text{ V}, R_{\text{G}} = 25 \Omega$ , Starting  $T_j = 25^\circ\text{C}$
3.  $I_{\text{SD}} \leq 12 \text{ A}, di/dt \leq 200 \text{ A}/\mu\text{s}, V_{\text{DD}} \leq BV_{\text{DS}}$ , Starting  $T_j = 25^\circ\text{C}$
4. Pulse Test : Pulse width  $\leq 300 \mu\text{s}$ , Duty Cycle  $\leq 2\%$
5. Essentially Independent of Operating Temperature Typical Characteristics





## TO-3PN MECHANICAL DATA



SYMBOL	MIN	NOM	MAX
A	4.60	4.80	5.00
b	0.80	1.00	1.20
b1	1.80	2.00	2.20
b2	2.80	3.00	3.20
c	0.55	0.60	0.75
c1	1.45	1.50	1.65
D	15.40	15.60	15.80
E	19.70	19.90	20.10
e	5.15	5.45	5.75
L1	3.30	3.50	3.70
L2	19.80	20.00	20.20
dP1	3.30	3.40	3.50
dP2	(3.20)		
Q	2.20	2.40	2.60
q1	4.80	5.00	5.20

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